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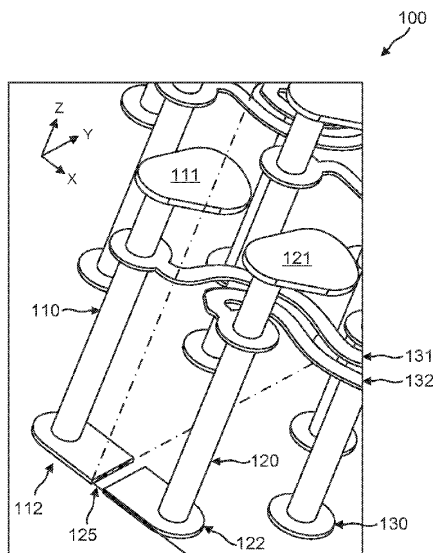


FIG. 1

(57) Abstract: An electrical device including a structure having a plural-
ity of dielectric layers, the structure further having a plurality of vertical
electrical connections extending from a top layer of the dielectric layers to
a bottom layer of the dielectric layers, a first vertical electrical connection
of the plurality of vertical electrical connections including a first capacitive
structure that extends in a plane perpendicular to a vertical dimension of the
vertical electrical connection, wherein the first capacitive structure is dis-
posed on a first dielectric layer of the plurality of dielectric layers, wherein
the first dielectric layer is below the top layer, and a second vertical electri-
cal connection of the plurality of vertical electrical connections including a
second capacitive structure extending in the plane and disposed on the first
dielectric layer.

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